

# FRFET TM

# FQP6N40CF/FQPF6N40CF 400V N-Channel MOSFET

#### **Features**

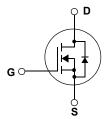
- 6A, 400V,  $R_{DS(on)} = 1.1 \Omega @V_{GS} = 10 V$
- Low gate charge (typical 16nC)
- · Low Crss (typical 15pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- · Fast recovery body diode (typical 70ns)

### **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, electronic lamp ballasts based on half bridge topology.





### **Absolute Maximum Ratings**

Symbol	Parameter			FQP6N40CF	FQPF6N40CF	Units
V <sub>DSS</sub>	Drain-Source Voltage		400		V	
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°	(C)	6	6*	Α
		- Continuous (T <sub>C</sub> = 100	)°C)	3.6	3.6*	Α
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	24	24*	А
V <sub>GSS</sub>	Gate-Source Voltage			± 30		V
E <sub>AS</sub>	Single Pulsed Avalanche Energy		(Note 2)	270		mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	6		А
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	73		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		(Note 3)	20		V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)			73	38	W
	- Derate above 25°C		0.58	0.3	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150		°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds			300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	FQP6N40CF	FQPF6N40CF	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.71	3.31	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQP6N40CF	FQP6N40CF	TO-220	-	-	50
FQPF6N40CF	FQPF6N40CF	TO-220F	-	-	50

### Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$_{S}$ = 0 V, $I_{D}$ = 250 μA = 250 μA, Referenced to 25°C $_{S}$ = 400 V, $V_{GS}$ = 0 V $_{S}$ = 320 V, $T_{C}$ = 125°C $_{S}$ = 30 V, $V_{DS}$ = 0 V $_{S}$ = -30 V, $V_{DS}$ = 0 V	400    	 0.54	  1 10	V V/°C μΑ μΑ
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	= 250 $\mu$ A, Referenced to 25°C $S = 400 \text{ V}$ , $V_{GS} = 0 \text{ V}$ $S = 320 \text{ V}$ , $T_{C} = 125$ °C $S = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$ $S = -30 \text{ V}$ , $V_{DS} = 0 \text{ V}$			 1 10	V/°C μA
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	S = 400 V, V <sub>GS</sub> = 0 V S = 320 V, T <sub>C</sub> = 125°C S = 30 V, V <sub>DS</sub> = 0 V S = -30 V, V <sub>DS</sub> = 0 V			1 10	μА
V <sub>D</sub>   V <sub>D</sub>	S = 320 V, T <sub>C</sub> = 125°C S = 30 V, V <sub>DS</sub> = 0 V S = -30 V, V <sub>DS</sub> = 0 V			10	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	S = 30 V, V <sub>DS</sub> = 0 V S = -30 V, V <sub>DS</sub> = 0 V				μА
$\begin{array}{c cccc} I_{GSSR} & Gate\text{-Body Leakage Current, Reverse} & V_G \\ \hline \textbf{On Characteristics} \\ V_{GS(th)} & Gate Threshold Voltage & V_D \\ R_{DS(on)} & Static Drain-Source & V_G \\ On-Resistance & On-Resista$	<sub>S</sub> = -30 V, V <sub>DS</sub> = 0 V			100	
On Characteristics         V <sub>GS(th)</sub> Gate Threshold Voltage         V <sub>D</sub> R <sub>DS(on)</sub> Static Drain-Source On-Resistance         V <sub>G</sub>					nA
V <sub>GS(th)</sub> Gate Threshold Voltage V <sub>D</sub> R <sub>DS(on)</sub> Static Drain-Source V <sub>G</sub> On-Resistance	<sub>S</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA			-100	nA
R <sub>DS(on)</sub> Static Drain-Source V <sub>G</sub> On-Resistance	<sub>S</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA				
R <sub>DS(on)</sub> Static Drain-Source V <sub>G</sub> On-Resistance		2.0		4.0	V
g <sub>FS</sub> Forward Transconductance V <sub>D</sub>	<sub>S</sub> = 10 V, I <sub>D</sub> = 3 A		0.9	1.1	Ω
	S = 40 V, I <sub>D</sub> = 3 A (Note 4		4.7		S
Dynamic Characteristics	-05//// -0//		100	005	
f_	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$		480	625	pF
Coss Output Capacitance			80	105	pF
C <sub>rss</sub> Reverse Transfer Capacitance			15	20	pF
Switching Characteristics					
	$V_{DD}$ = 200 V, $I_{D}$ = 6 A, $R_{G}$ = 25 $\Omega$		13	35	ns
$t_r$ Turn-On Rise Time			65	140	ns
t <sub>d(off)</sub> Turn-Off Delay Time			21	55	ns
t <sub>f</sub> Turn-Off Fall Time	(Note 4, 5		38	85	ns
	$V_{DS} = 320 \text{ V}, I_D = 6 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)		16	20	nC
Q <sub>gs</sub> Gate-Source Charge			2.3		nC
Q <sub>gd</sub> Gate-Drain Charge			8.2		nC
Drain-Source Diode Characteristics and Maximum Ratings	5				
I <sub>S</sub> Maximum Continuous Drain-Source Diode Fo	Maximum Continuous Drain-Source Diode Forward Current			6	Α
I <sub>SM</sub> Maximum Pulsed Drain-Source Diode Forward	d Current			24	Α
V <sub>SD</sub> Drain-Source Diode Forward Voltage V <sub>G</sub>	<sub>S</sub> = 0 V, I <sub>S</sub> = 6 A			1.4	V
	3 - 1, 13 - 1 1				v
Q <sub>rr</sub> Reverse Recovery Charge	<sub>S</sub> = 0 V, I <sub>S</sub> = 6 A,		70		ns

#### Notes:

- ${\it 1. Repetitive Rating: Pulse width limited by maximum junction temperature}\\$
- 2. L = 13.7mH, I $_{AS}$  = 6A, V $_{DD}$  = 50V, R $_{G}$  = 25  $\Omega$ , Starting T $_{J}$  = 25°C
- 3. I  $_{SD}$   $\leq$  6A, di/dt  $\leq$  200A/ $\mu s$ ,  $V_{DD}$   $\leq$  BV $_{DSS,}$  Starting  $T_{J}$  = 25°C
- 4. Pulse Test : Pulse width  $\leq 300 \mu s,$  Duty cycle  $\leq 2\%$
- 5. Essentially independent of operating temperature

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

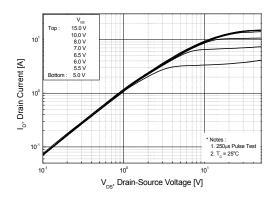
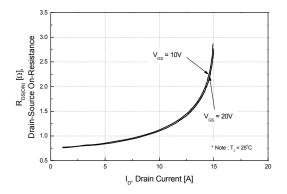


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage



**Figure 5. Capacitance Characteristics** 

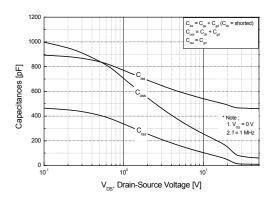


Figure 2. Transfer Characteristics

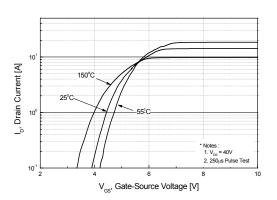


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

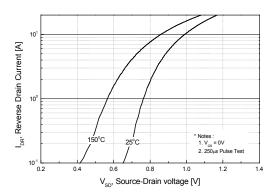
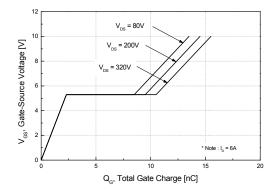


Figure 6. Gate Charge Characteristics



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

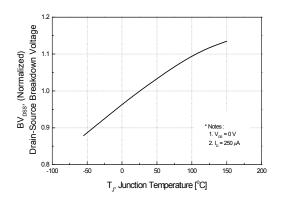


Figure 8. On-Resistance Variation vs. Temperature

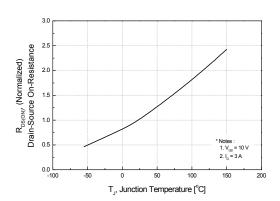


Figure 9-1. Maximum Safe Operating Area for FQP6N40CF

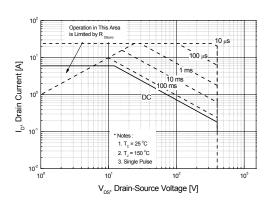


Figure 9-2. Maximum Safe Operating Area for FQPF6N40CF

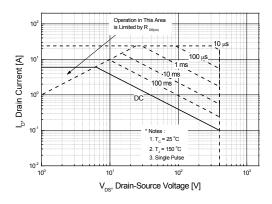
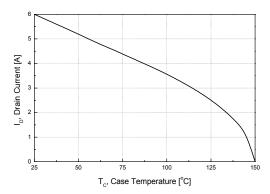


Figure 10. Maximum Drain Current vs. Case Temperature



# **Typical Performance Characteristics (Continued)**

Figure 11-1. ransient Thermal Response Curve for FQP6N40CF

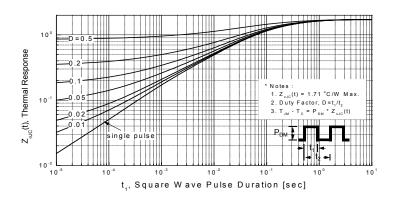
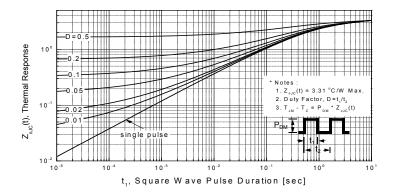
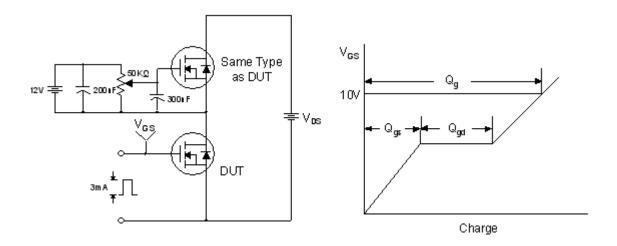


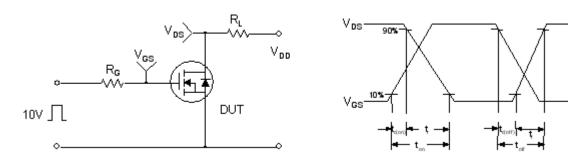
Figure 11-2. Transient Thermal Response Curve for FQPF6N40CF



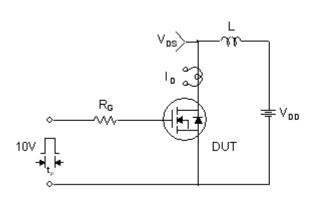
### **Gate Charge Test Circuit & Waveform**

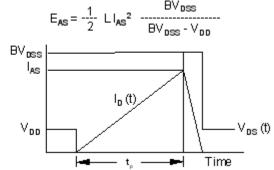


### **Resistive Switching Test Circuit & Waveforms**

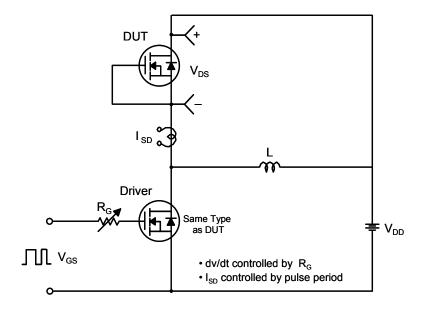


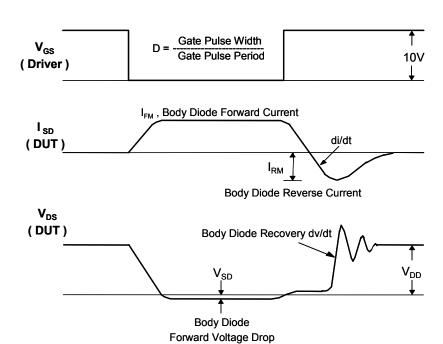
### **Unclamped Inductive Switching Test Circuit & Waveforms**





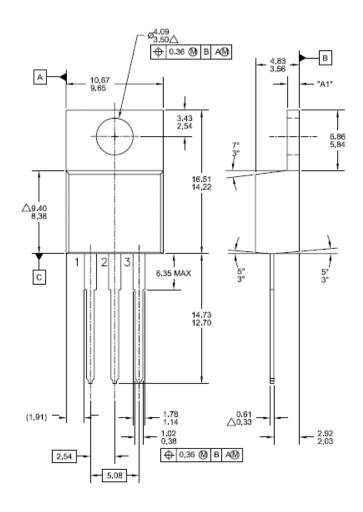
### Peak Diode Recovery dv/dt Test Circuit & Waveforms

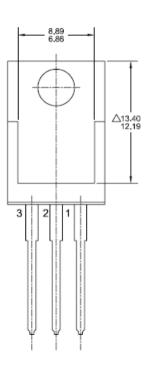


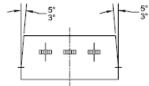


# **Mechanical Dimensions**

# TO-220



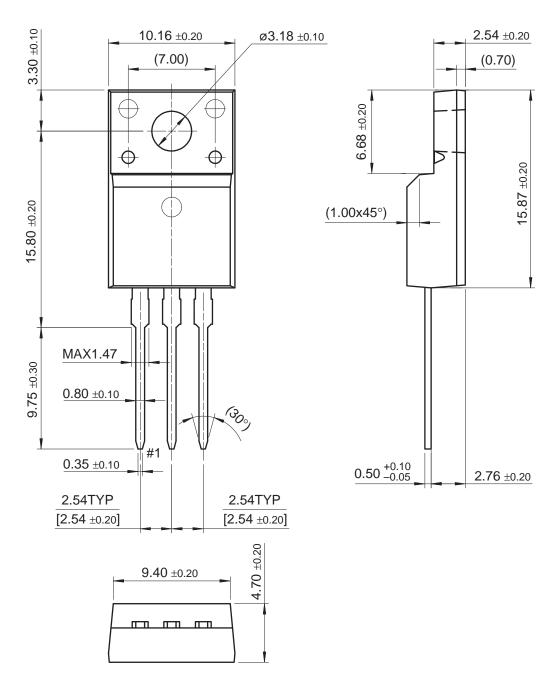




**Dimensions in Millimeters** 

# **Mechanical Dimensions** (continued)

# TO-220F



Dimensions in Millimeters





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